



Tin-Lead Solder Paste

SH-6209RMA

Rev. 2016/03/01 Ver. 02-01

BASIC OVERVIEW



Sn62Pb36Ag2 Solder Paste
 Low Halide Content
 No Clean
 Low Voiding

APPLICATIONS

Universal Tin-Lead SMD Solder Paste
 Wide Range of Applications and PCB designs

FEATURES

Appearance	Gray paste w/o visible foreign and clusters	
Alloy Composition	Sn62/Ag2/Pb36	JIS-Z-3282
Melting Point	179~189 °C	DSC
Particle Size	(Type 3) +45μm < 1% , - 20μm < 10% (Type 4) +38μm < 1% , - 20μm < 10%	IPC-TM-650, 2.2.14
Powder Shape	Spherical	
Flux Content	10.0 ± 1.0 wt%	JIS-Z-3197, 6.1.
Halide Content	<0.5 wt% (in flux)	J-STD-004
Viscosity	200 ± 30 Pa.s (25±1°C, 10rpm, Malcom)	JIS-Z-3284 Annex 6
Flux Type	ROL1	J-STD-004

Alloy Detail Composition

(Sn)	(Ag)	(Pb)	(Cu)	(Zn)	(Al)	(Sb)	(Fe)	(As)	(Bi)	(Cd)
62.0 ± 0.5	2.0 ± 0.2	REM.	0.05 MAX	0.001 MAX	0.001 MAX	0.05 MAX	0.02 MAX	0.03 MAX	0.1 MAX	0.002 MAX

(wt%)

Scan Code for Solder
 Paste Documents





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PERFORMANCE & RELIABILITY

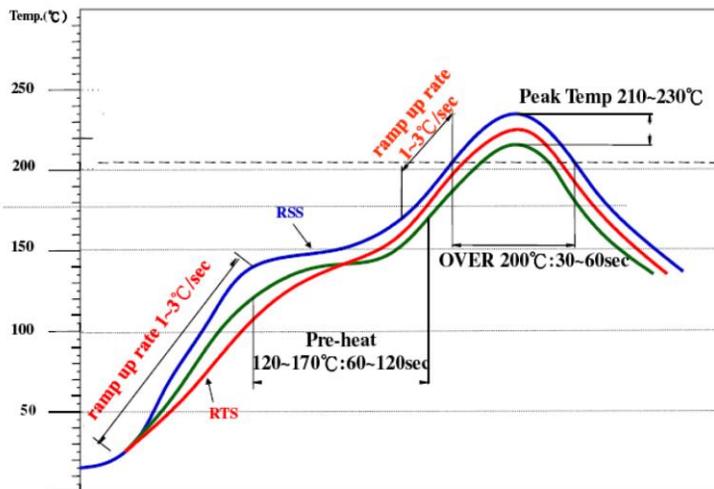
Copper Plate Corrosion Test	Pass	JIS-Z-3197, 6.6.1
Spreading Test	> 90%	JIS-Z-3197, 6.10
Silver Chromate Test	Pass	IPC-TM-650, 2.3.33
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32
Fluorides By Spot Test	Pass	IPC-TM-650, 2.3.35.1
Viscosity Test (25°C, 10 rpm)	200 ± 30 Pa.s	JIS-Z-3284. Annex 6
Tackiness Test (gf)	> 120 (8hr)	JIS-Z-3284. Annex 9
Slump Test	Less than 0.3 mm	JIS-Z-3284. Annex 8
Solder Ball Test	Pass	JIS-Z-3284. Annex 11

S.I.R. Test	▲	> 1 x 10 ⁹ Ω, Pass	IPC-TM-650, 2.6.3.3
Electro Migration Test	◆	> 1 x 10 ¹² Ω, Pass	IPC-TM-650, 2.6.14.1

▲ Test Conditions : 85 °C, 85% RH

◆ Test Conditions: 65°C, 85% RH

RECOMMENDED REFLOW PROFILE



Ramp Up Rate (120-170°C): 1.0-3.0 °C/sec

Pre-heating Time (120-170°C): 60-120 sec

Time Period Above 200°C: 30-60 sec

Ramp Up Rate (210-230°C) : 1.0-3.0 °C/sec

Peak Temperature: 210-230 °C

Ramp Down Cooling Rate: 1.0-3.0 °C/sec

Note: The recommended reflow profile is provided as a guideline. Optimal profile may differ due to oven type, assembly layout or other process variables.



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STORAGE & HANDLING:

- Refrigerate the solder paste at 0-10°C. Shelf life is 6 months from production date (sealed package).
- Keep away of direct sunlight.
- Allow the paste to reach defined printing temperature (room temperature) for 3-4 hrs. Do not heat up the solder paste rapidly.
- For jars packaging, mix the solder paste before use for 1-3 mins by plastic spatula.
- It is recommended to finish fresh paste within 24 hrs. Do not store used paste and fresh paste in the same jar.
- If printing process was interrupted for more than 1 hour, remove the remained paste from stencil and seal in the jar.
- Recommended printing environment is 22-28°C and RH 30-60%.

Note: For more information, please refer to solder paste application guideline sheet

HOW TO ORDER

SH-6209 – RMA – T3 – 500

Solder Alloy	Flux	Particle Size	Weight / Packaging
SH-6209 = Sn62/Pb36/Ag2	RMA = ROL1	T3 = 20-45µm T4 = 20-38µm	30 = syringe 30g 100 = syringe 100g 150 = syringe 150g 250 = plastic jar 250g 500 = plastic jar 500g 600 = small cartridge 600g 1200 = large cartridge 1200g



CONTACTS

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